

Contents

<i>List of Contributors</i>	ix
<i>Preface</i>	xi

Part I

I-1 Introduction

J. L. Vossen

I. The Organization of This Book	3
II. Other Film Deposition Processes	5
References	5

Part II PHYSICAL METHODS OF FILM DEPOSITION

II-1 Glow Discharge Sputter Deposition

J. L. Vossen and J. J. Cuomo

I. Introduction	12
II. Physical and Chemical Effects of Ion Bombardment on Surfaces	14
III. Glow Discharges	24
IV. Equipment Configuration	31
V. Preconditioning of Targets, Substrates, and Systems for Film Deposition	41
VI. The Sputtering Gas	46
VII. Deposition with Simultaneous Ion Bombardment of the Substrate and Growing Film	50
VIII. Rate and Uniformity of Deposition	61
IX. Conclusion	62
References	62

II-2 Cylindrical Magnetron Sputtering*John A. Thornton and Alan S. Penfold*

I. Introduction	76
II. Principles of Operation	79
III. Cylindrical Magnetron Apparatus	90
IV. Plasma Discharge	94
V. RF Operation	98
VI. Erosion and Deposition Profiles	99
VII. Coating Deposition	102
VIII. Reactive Sputtering	107
IX. Summary	109
References	110

II-3 The Sputter and S-Gun Magnetrons*David B. Fraser*

I. Introduction	115
II. Description	116
III. Operational Characteristics	117
IV. Bias Operation	121
V. Film Deposition	126
VI. Conclusions	128
References	128

II-4 Planar Magnetron Sputtering*Robert K. Waits*

I. Introduction	131
II. DC Planar Magnetron Sputtering	134
III. RF Planar Magnetron Sputtering	163
IV. Applications	167
V. Conclusions	170
References	170

II-5 Ion Beam Deposition*James M. E. Harper*

I. Introduction	175
II. Ion Beam Generation	176
III. Secondary Ion Beam Deposition	189
IV. Primary Ion Beam Deposition	198
V. Concluding Comments	203
References	204

Part III CHEMICAL METHODS OF FILM DEPOSITION**III-1 Deposition of Inorganic Films from Solution***Frederick A. Lowenheim*

I. Introduction	209
II. Deposition by Chemical Reactions	210
III. Deposition by Electrochemical Reactions	229
IV. Conclusion	254
References	255

III-2 Chemical Vapor Deposition of Inorganic Thin Films*Werner Kern and Vladimir S. Ban*

I. Introduction	258
II. Fundamental Aspects of CVD	259
III. CVD Reactor Systems	278
IV. CVD of Insulators	290
V. CVD of Semiconductors	309
VI. CVD of Conductors	315
VII. CVD of Miscellaneous Materials	317
VIII. Conclusions	319
References	320

Part IV PHYSICAL-CHEMICAL METHODS OF FILM DEPOSITION**IV-1 Plasma Deposition of Inorganic Thin Films***J. R. Hollahan and R. S. Rosler*

I. Introduction	335
II. Experimental Requirements and Techniques	337
III. Deposition of Thin Inorganic Films	342
IV. Conclusions, Applications, and Prospects	357
References	358

IV-2 Glow Discharge Polymerization*H. Yasuda*

I. Introduction	361
II. Characteristic Aspects of Glow Discharge Polymerization	362
III. Processing Factors of Glow Discharge Polymerization	367
IV. Organic Compounds for Glow Discharge Polymerization	377
V. Dependence of Glow Discharge Polymerization on Processing Factors	381
References	396

Part V ETCHING PROCESSES**V-1 Chemical Etching***Werner Kern and Cheryl A. Deckert*

I. Introduction	401
II. Principles and Techniques of Etching	403
III. Chemical Etching of Specific Materials	413
IV. Tables of Etchants and Etching Conditions	433
V. Summary and Conclusions	481
References	481

V-2 Plasma-Assisted Etching Techniques for Pattern Delineation*C. M. Melliar-Smith and C. J. Mogab*

I. Introduction	497
II. Physical and Chemical Phenomena in Low Pressure Plasmas	499
III. The Design of Etching Equipment	506
IV. Process Parameters	512
V. Pattern Edge Profiles	537
VI. Advantages and Disadvantages of Plasma-Assisted Etching	548
References	552

Index

557